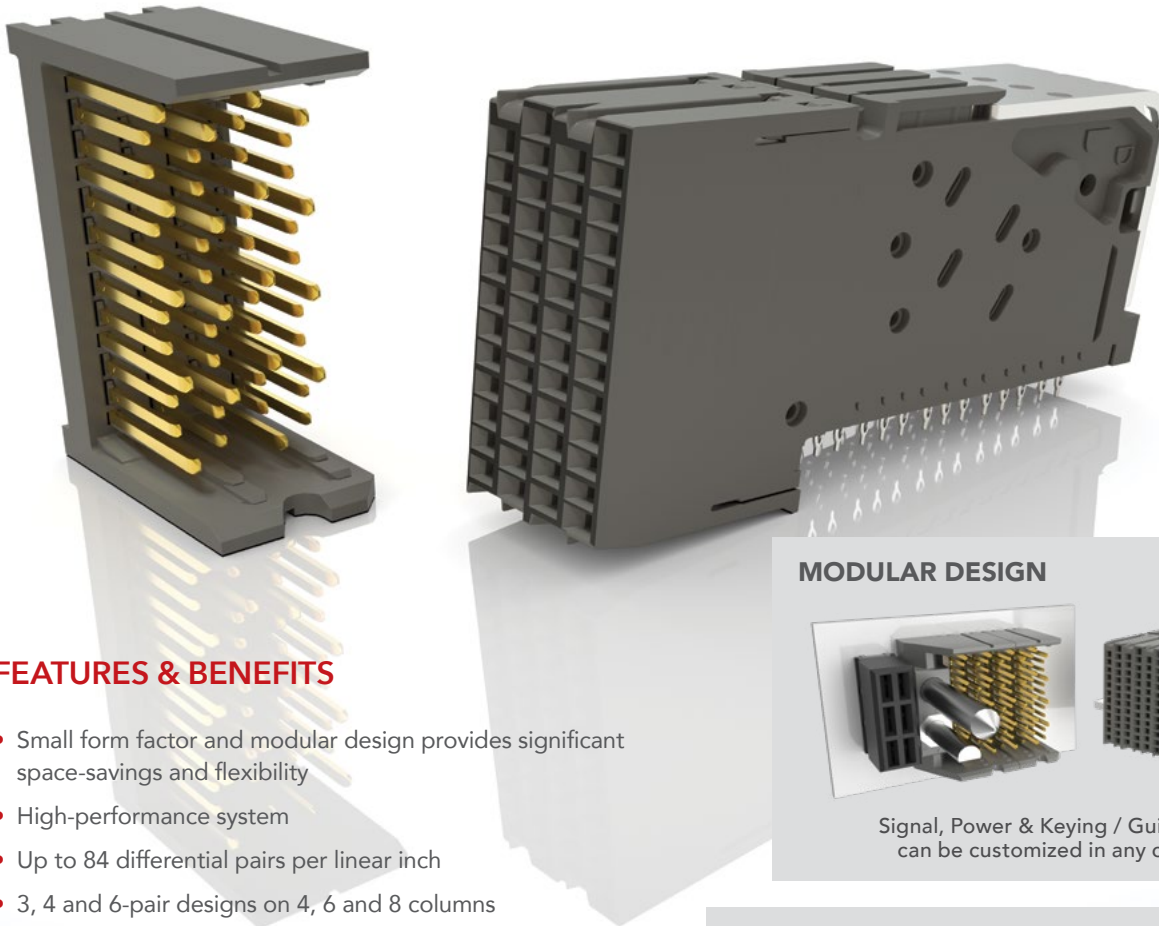


## HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

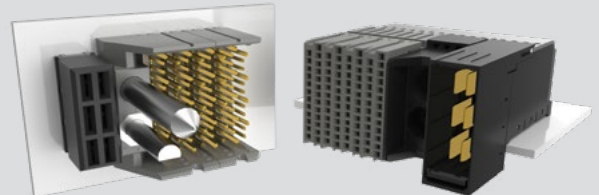
16  
Gbps



### FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit [samtec.com?BSP](http://samtec.com?BSP) or contact [HSBP@samtec.com](mailto:HSBP@samtec.com)
- Press-fit extraction and insertion tool options; please visit [samtec.com/tooling](http://samtec.com/tooling) for details

### MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

### HIGH-DENSITY, SMALL FORM FACTOR



**XCede<sup>®</sup> HD**  
Up to 84 pairs per linear inch



**Traditional Backplane**  
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

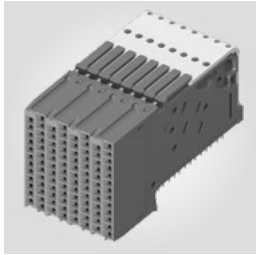
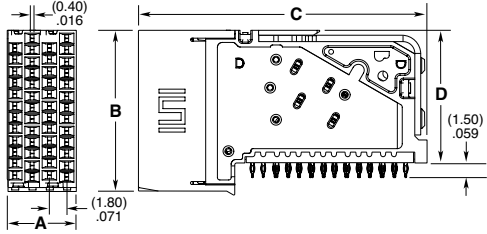
### KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
HDTM/HDTF	LCP	Phosphor Bronze (HDTM) Copper Alloy (HDTF)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C	1.5 A per contact	48 VAC
HPTS/HPTT	LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-40 °C to + 105 °C	10 A per blade	48 VAC

## (1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE RECEPTACLE

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	-3, -4, -6	-04, -06, -08	-S = 30 μ" (0.76 μm) Gold on Contact Area, Matte Tin on Tail		-LC = Standard  -HS = High-Speed	-100 = 100 Ω  -085 = 85 Ω

**HDTF Board Mates:**  
HDTM

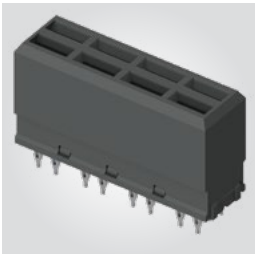
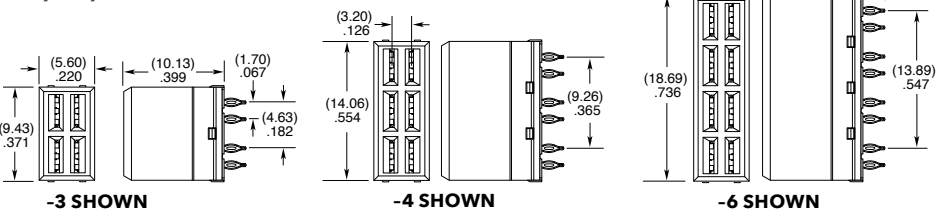
NO. OF COLUMNS	A	PAIRS PER COLUMN	B	C	D
-04	(7.2) .283	-3	(12.8) .504	(26.0) 1.02	(9.9) .390
-06	(10.8) .425	-4	(16.4) .646	(29.4) 1.16	(13.5) .531
-08	(14.4) .567	-6	(23.6) .929	(36.6) 1.44	(20.7) .815

View complete specifications at: [samtec.com?HDTF](http://samtec.com?HDTF)

## (3.20 mm) .126" PITCH • POWER MODULES

HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
= Socket	Based on Pair Count of Signal Modules (HDTM)	-S = Standard Gold on Contact Area, Matte Tin on Tail		-VT = Vertical


**HPTS Mates with:**  
HPTT, BSP

View complete specifications at: [samtec.com?HPTS](http://samtec.com?HPTS)

HPTT	BODY HEIGHT	PLATING	POSITION NO. 1	POSITION NO. 2	POSITION NO. 3	POSITION NO. 4	D	ORIENTATION
= Terminal	Based on Pair Count of Signal Modules (HDTF, BSP)	-S = Standard Gold on Contact Area, Matte Tin on Tail	Contact Wipe Column A & B	Contact Wipe Column A & B	Contact Wipe Column A & B (-4 & -6 Height Only)	Contact Wipe Column A & B (-6 Height Only)		-RA = Right-angle
	-3, -4, -6		-3 = (4.5 mm) 0.18"  -6 = (5.5 mm) 0.22"	-3 = (4.5 mm) 0.18"  -6 = (5.5 mm) 0.22"	-3 = (4.5 mm) 0.18"  -6 = (5.5 mm) 0.22"	-3 = (4.5 mm) 0.18"  -6 = (5.5 mm) 0.22"		

**HPTT Mates With:**  
HPTS



**Notes:**  
Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

View complete specifications at: [samtec.com?HPTT](http://samtec.com?HPTT)

